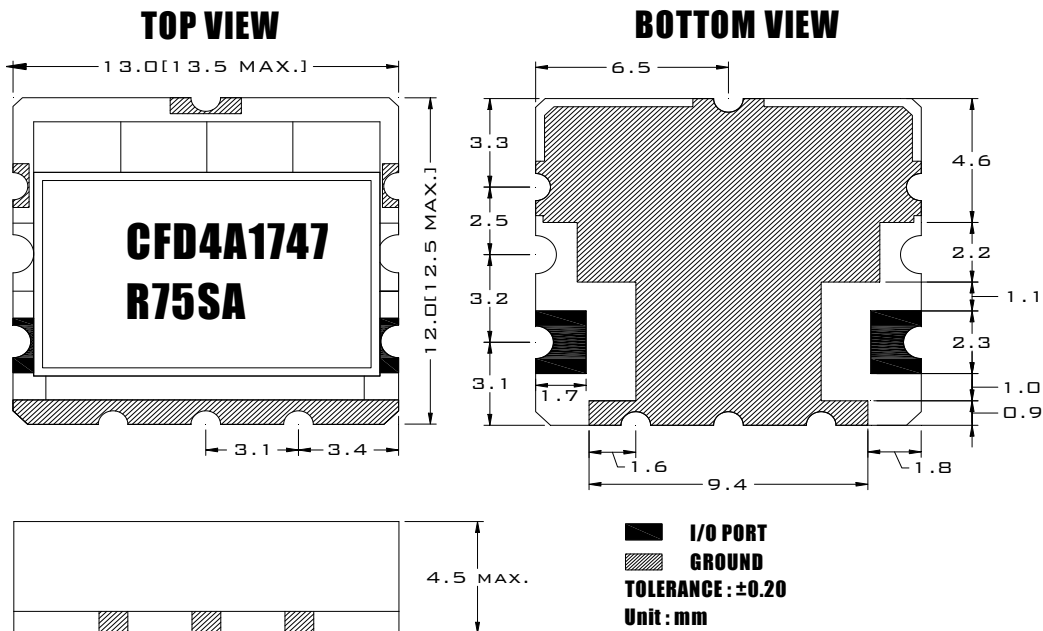


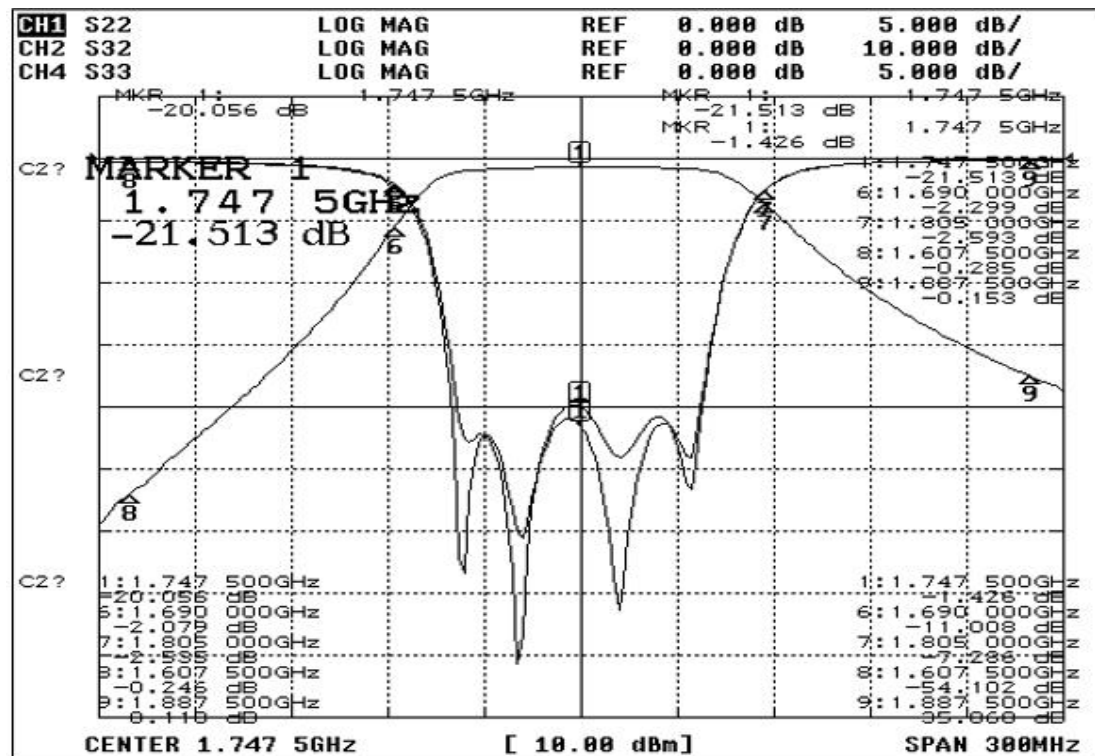
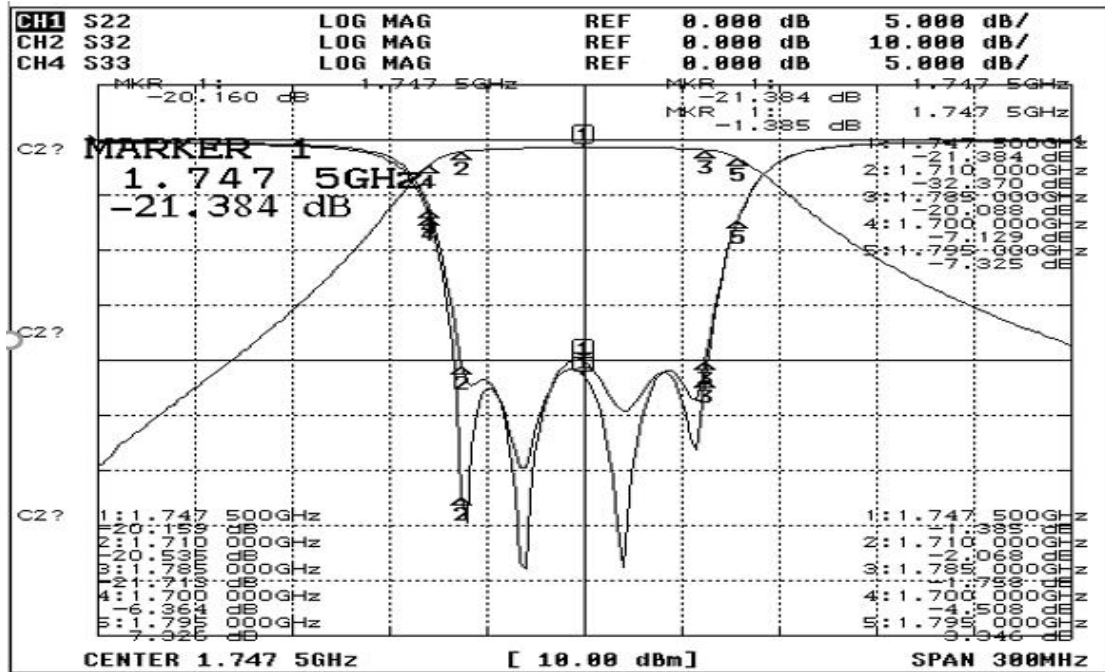
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	1747.5	MHz
Bandwidth [BW]	fo ±37.5 [1710 ~ 1785]	MHz
Insertion Loss in BW	2.5	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	2.0dB min @ fo ±47.5 [1700~1795]	MHz
	5.0dB min @ fo ±57.5 [1690~1805]	MHz
	32dB min @ fo ±140 [1607.5~1887.5]	MHz
	dB min @ fo ± [ ~ ]	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

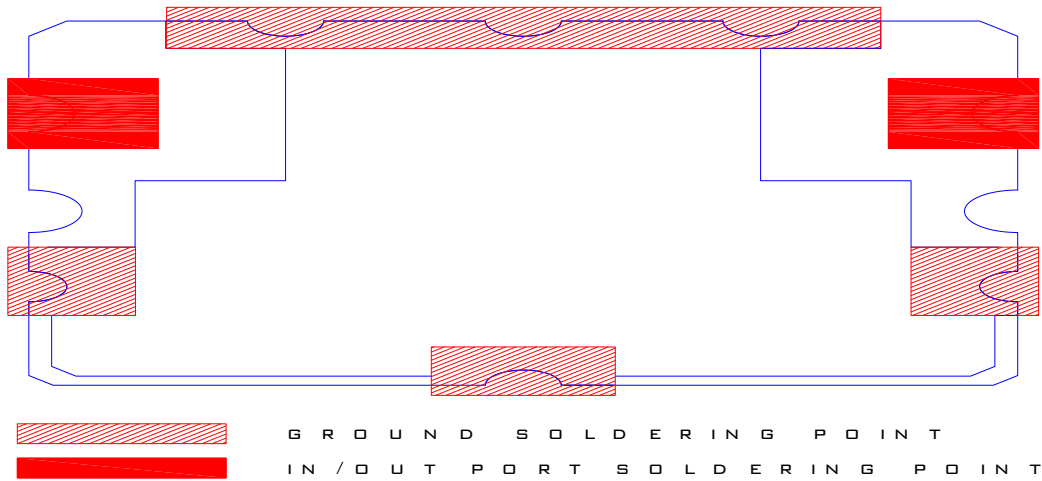
Mechanical Specification



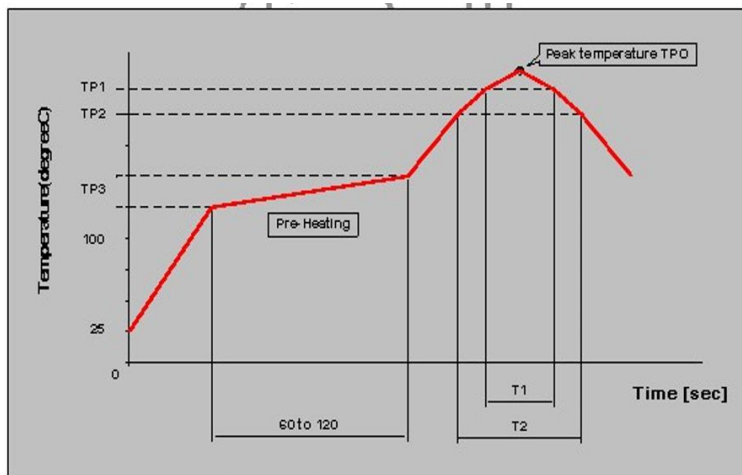
Plot Data



Recommneded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180